



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

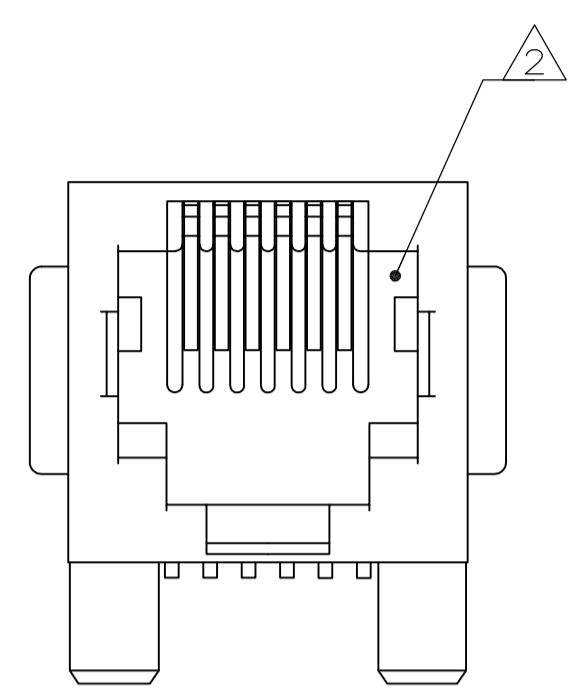
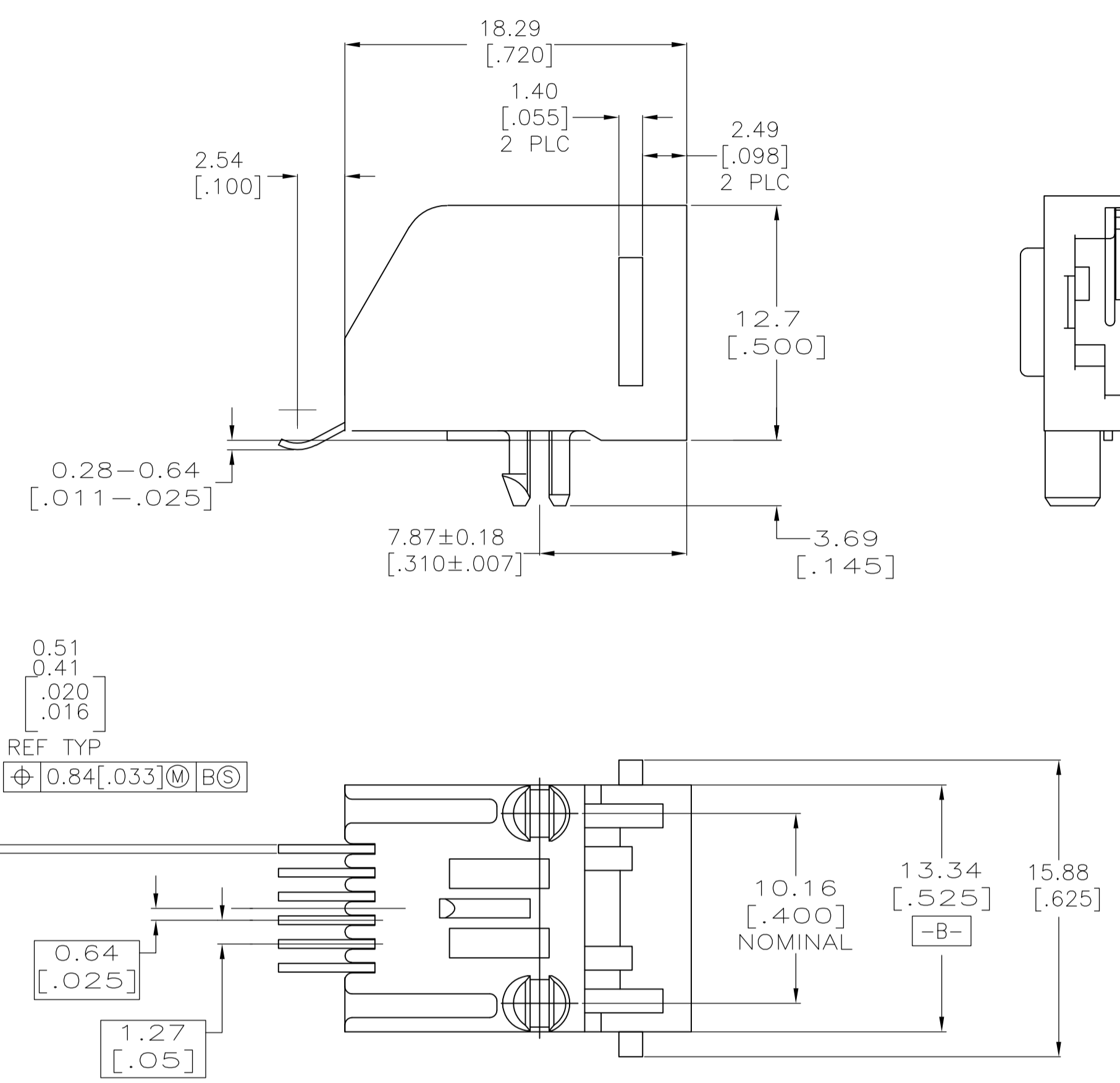
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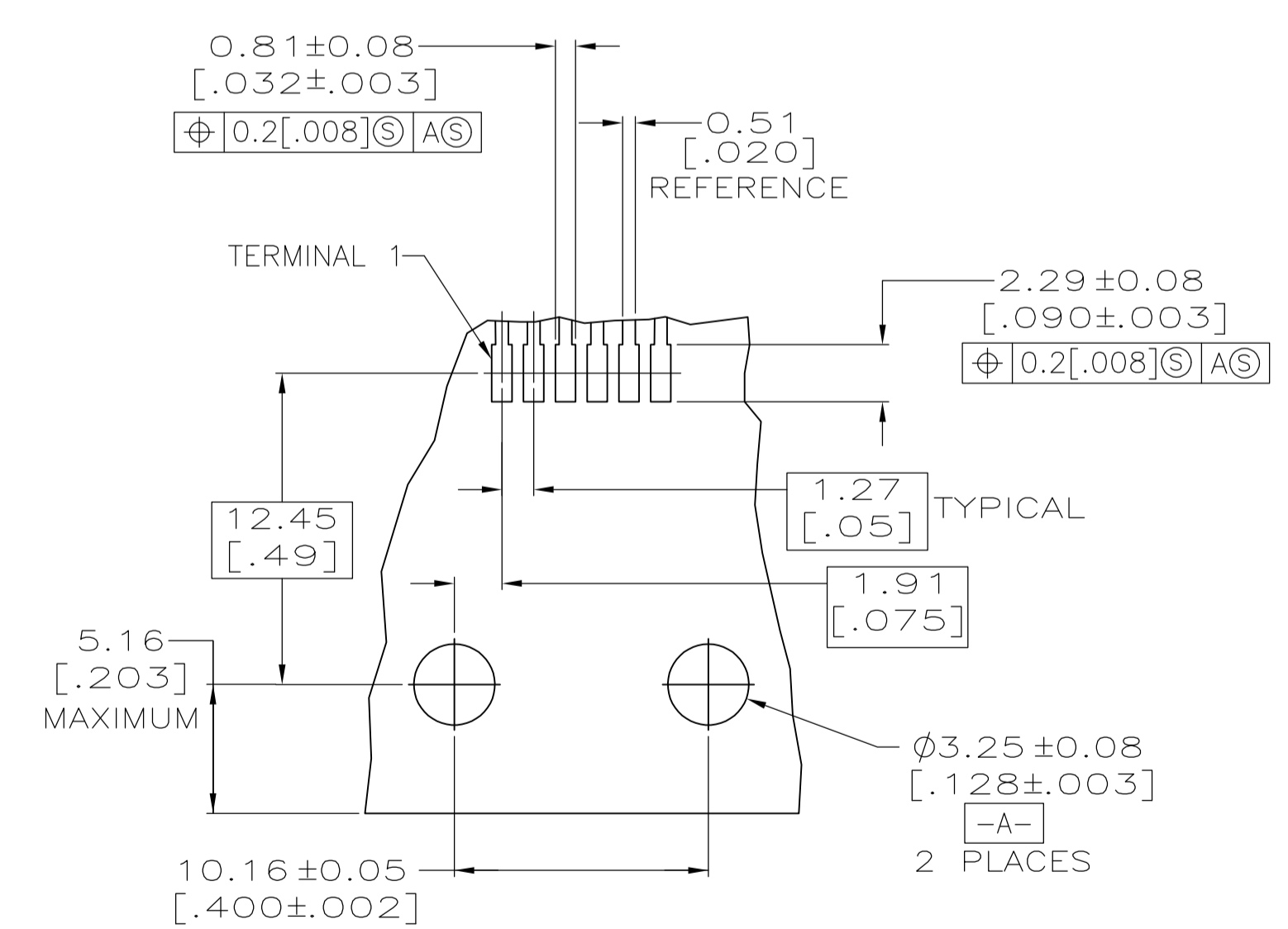
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



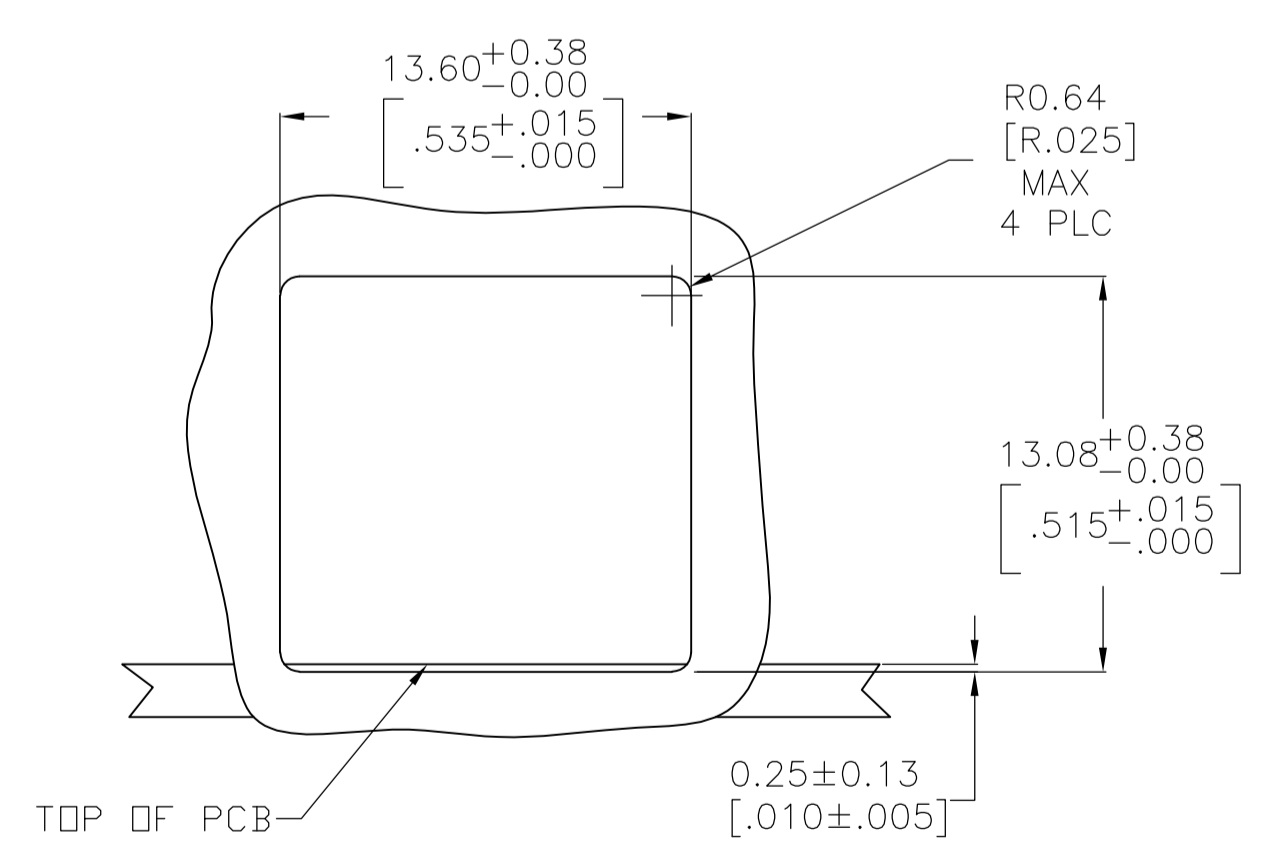
| LOC | | DIST | | REVISIONS | | | |
|-----|---------------------------|------|---------|-----------|-----|------|--|
| AA | 00 | REV | DATE | BY | CHK | APPV | |
| B1 | REVISED PER ECO-11-005033 | | 23MAR11 | RK | HMR | | |



- MATERIAL: HOUSING- HTN MOLDING COMPOUND, 94VO, COLOR: BLACK.
TERMINAL- 0.36 [.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SNAP-IN RETENTION FEATURE ACCOMMODATES A 1.57±0.13 [.062±.005] THICK PRINTED CIRCUIT BOARD.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- TERMINALS ASSEMBLED IN CENTER POSITIONS FOR -2.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

| | |
|---------------------|-------------|
| 4 | 5555077-2 |
| 6 | 5555077-1 |
| NUMBER OF TERMINALS | PART NUMBER |

| | | | | | |
|--|--|--|--|---|--|
| THIS DRAWING IS A CONTROLLED DOCUMENT. | | DIN G. ATTADIA - 07JUN2005 | | STE TE Connectivity | |
| DIMENSIONS: mm [INCHES] | | TOLERANCES UNLESS OTHERWISE SPECIFIED: | | APVD S. FLICKINGER 07JUN2005 | |
| 0 PLC ± - | | 1 PLC ± - | | NAME: MODULAR JACK ASSEMBLY, 6 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT W/ PANEL STOPS | |
| 1 PLC ± - | | 2 PLC ± - | | PRODUCT SPEC: 108-1163 | |
| 2 PLC ± - | | 3 PLC ± - | | APPLICATION SPEC: 114-6040 | |
| 3 PLC ± - | | 4 PLC ± - | | SIZE: A1 | |
| 4 PLC ± - | | ANGLES ± - | | CAGE CODE: 00779 | |
| MATERIAL: SEE NOTE 1 | | FINISH: SEE NOTE 1 | | DRAWING NO: 5555077 | |
| | | WEIGHT: - | | RESTRICTED TO: - | |
| | | CUSTOMER DRAWING | | SCALE: 4:1 SHEET 1 OF 1 REV B1 | |